

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT										
NATURE OF CONVEYANCE:	ASSIGNMENT										
CONVEYING PARTY DATA											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Bin-Juine Huang</td> <td>07/20/2007</td> </tr> <tr> <td>Huan-Hsiang Huang</td> <td>07/20/2007</td> </tr> <tr> <td>Fu-Sheng Sun</td> <td>07/20/2007</td> </tr> <tr> <td>Yi-Hai Lian</td> <td>07/20/2007</td> </tr> </tbody> </table>		Name	Execution Date	Bin-Juine Huang	07/20/2007	Huan-Hsiang Huang	07/20/2007	Fu-Sheng Sun	07/20/2007	Yi-Hai Lian	07/20/2007
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Huan-Hsiang Huang	07/20/2007										
Fu-Sheng Sun	07/20/2007										
Yi-Hai Lian	07/20/2007										
RECEIVING PARTY DATA											
Name:	Advanced Thermal Device Inc.										
Street Address:	B2F, No.3, Wanning St., Wunshan District,										
City:	Taipei City										
State/Country:	TAIWAN										
Postal Code:	116										
PROPERTY NUMBERS Total: 1											
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11831973</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11831973						
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Application Number:	11831973										
CORRESPONDENCE DATA											
Fax Number:	(949)660-0809										
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>											
Phone:	886223692800										
Email:	usa@jcipgroup.com.tw										
Correspondent Name:	JIANQ CHYUN INTELLECTUAL PROPERTY										
Address Line 1:	7F-1,NO.100,ROOSEVELT RD.,SEC.2,										
Address Line 4:	Taipei, TAIWAN 100										
ATTORNEY DOCKET NUMBER:	24113-US-PA										
NAME OF SUBMITTER:	Belinda Lee										
<p>Total Attachments: 2 source=24113assignment#page1.tif</p>											

CH \$40.00 11831973

500329987

**PATENT
 REEL: 019661 FRAME: 0743**

ASSIGNMENT

WHEREAS,

- | | |
|--------------------|----------------------|
| 1. Bin-Juine Huang | 2. Huan-Hsiang Huang |
| 3. Fu-Sheng Sun | 4. Yi-Hai Lian |

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **EVAPORATOR, LOOP HEAT PIPE MODULE AND HEAT GENERATING APPARATUS**

Filed: Serial No.

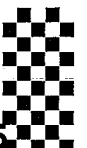
Executed concurrently with the execution of this instrument

WHEREAS, Advanced Thermal Device Inc.
of B2F, No.3, Wanning St., Wunshan District, Taipei City 116, Taiwan (R.O.C.)

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.



ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Bin-Juine Huang Date: July 20, 2007
Sole or First Joint Inventor: Bin-Juine Huang

Signature: Huan-Hsiang Huang Date: July 20, 2007
Second Joint Inventor (if any): Huan-Hsiang Huang

Signature: Fu-Sheng Sun Date: July 20, 2007
Third Joint Inventor (if any): Fu-Sheng Sun

Signature: Yi-Hai Lian Date: July 20, 2007
Fourth Joint Inventor (if any): Yi-Hai Lian